

SMD Power Inductor

TMIM322512HL-Series(B)

1. Features

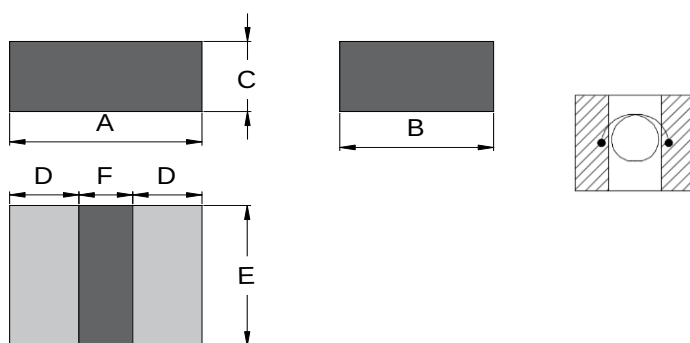
1. Low loss realized with low DCR.
2. High performance realized by metal dust core.
3. Ultra low buzz noise, due to composite construction.
4. 100% Lead(Pb)-Free & Halogen-Free and RoHS compliant.
5. Operating temperature: -40~+125℃ (Including self - temperature rise)



2. Applications

Commercial applications

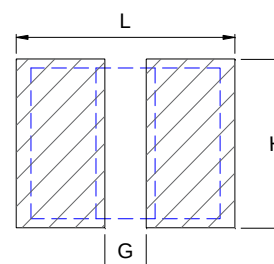
3. Dimension



A	B	C	D	E	F
3.2±0.3	2.5±0.3	1.0±0.2	1.1±0.3	2.5±0.3	1.0Min

Unit : mm

Recommend PC Board Pattern



L	G	H
3.7	0.7	2.8

Note:

1. PCB layout is referred to standard IPC-7351B
2. The above PCB layout reference only.
3. Recommend solder paste thickness at 0.10mm and above.

4. Part Numbering

TMIM	322512	HL	-	1R0	M	B
A	B	C		D	E	F

A: Series
 B: Dimension
 C: Type
 D: Inductance
 E: Inductance Tolerance
 F: Black

AxBxC
 HL: High current, low dcr
 1R0=1.00uH
 M=±20%

5. Specification

Tai-Tech Part Number	Inductance (uH) $\pm 20\%$ @ 0 A DC	Irms(A)		Isat (A)		DCR(m Ω)	
		Typ	Max	Typ	Max	Typ	Max
TMIM322512HL-R22MB	0.22	9.5	9.0	9.3	8.7	7.4	8.5
TMIM322512HL-R33MB	0.33	8.5	8.0	9.2	8.6	9	12
TMIM322512HL-R47MB	0.47	7.1	6.6	8.3	7.5	17	19
TMIM322512HL-R68MB	0.68	6.3	5.8	7.4	6.9	19	24
TMIM322512HL-1R0MB	1.00	5.7	5.2	6.6	5.8	26	30
TMIM322512HL-1R5MB	1.50	4.6	4.0	5.3	5.0	40	50
TMIM322512HL-2R2MB	2.20	4.2	3.7	4.9	4.4	58	70
TMIM322512HL-3R3MB	3.30	3.2	2.8	3.5	3.1	75	95
TMIM322512HL-4R7MB	4.70	2.5	2.0	2.9	2.5	115	135
TMIM322512HL-6R8MB	6.80	2.1	1.9	2.8	2.4	177	210
TMIM322512HL-100MB	10.0	2.2	1.8	2.3	1.9	210	230

Note:

1. Test frequency : L_s : 1MHz /1.0V.
2. All test data referenced to 25°C ambient.
3. Testing Instrument(equ.) : Agilent 4284A, E4991A, 4339B, KEYSIGHT E4980A/AL, chroma3302, 3250, 16502.
4. Heat Rated current (Irms) will cause the coil temperature rise approximately ΔT of 40°C.
5. Saturation current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions.Circuit design, component, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. Irms Testing : temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components. Therefore temperature rise should be verified in application conditions.
8. Rated DC current : the lower value of Irms and Isat

6. Typical Performance Curves

